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SUBMISSION TYPE:			NEW ASSIGNMENT			
NATURE OF CONVEYANCE:		,	ASSIGNMENT			
CONVEYING PAR	ΤΥ DATA					
N			me	Execution Date		
Michael Bauer				09/11/2006		
Ludwig Heitzer		09/14/2006				
Jens Pohl		09/11/2006				
Peter Strobel		09/11/2006				
Christian Struempfl				09/11/2006		
RECEIVING PART	Y DATA					
Name:	Infineon Tec	Infineon Technologies AG				
Street Address:	StMartin-St	StMartin-Str. 53				
City:	Muenchen	Muenchen				
State/Country:	GERMANY	GERMANY				
Postal Code:	81669					
Property Type			Number			
Application Number: 1		1146554	1465547			
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Correspondent Name: Steven E. Dicke Address Line 1: 100 South 5th Street						
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Address Line 4:	Minneapolis, MINNESOTA 55402					
ATTORNEY DOCKET NUMBER:			I431.171.101/FIN760US			
NAME OF SUBMITTER:			Steven E. Dicke			
				PATENT		
500173366				REEL: 018472 FRAME: 000	09	

ASSIGNMENT

For good and valuable consideration, I, Michael Bauer, a citizen of Germany, residing at Dachgred 31, 93152 Nittendorf, Germany; Ludwig Heitzer, a citizen of Germany, residing at Augustenstrasse 15, 93049 Regensburg, Germany; Jens Pohl, a citizen of Germany, residing at Sudetenstr. 5a, 93170 Bernhardswald, Germany; Peter Strobel, a citizen of Germany, residing at Weissgerbergraben 4, 93047 Regensburg; and Christian Stuempfl, a citizen of Germany, residing at Hertzstr. 17, 92421 Schwandorf, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to Infineon Technologies AG, a corporation, organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Str. 53, 81669 Munich, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and was filed on August 18, 2006 as U.S. Application No. 11/465,547, entitled:

SEMICONDUCTOR DEVICE WITH A THINNED SEMICONDUCTOR CHIP AND METHOD FOR PRODUCING THE THINNED SEMICONDUCTOR CHIP

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, it successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: Michael Bauer DATE: M. G. 2006

PATENT REEL: 018472 FRAME: 0011

INFINEON REF NO. FIN760US O.C. REF NO. I431.171.101

SIGNATURE:	NAME: Ludwig Heitzer	DATE: <u>14.09,2006</u>
SIGNATURE:	NAME: Jens Pahl	DATE: 11. 09. 2006
SIGNATURE:	Ale Alel NAME: Peter Strobel	DATE: <u>M.09. Roo6</u>
SIGNATURE:	NAME: Christian Stuempfl	DATE: 11.09.2006

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RECORDED: 11/02/2006